

08-27-2002



102202158

To the Assistant Commissioner for Patents

SHEET

Attorney Docket No. 5000-1-263

1. Name of conveying party(ies):

Yu-Sik KIM; Joong-Hee LEE

8-21-02

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name

Other: \_\_\_\_\_

Execution Date: 4/19/02; 4/19/02

2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRONIC CO., LTD.

Address: 416, MAETAN-DONG, PALDAL-GU

SUWON-CITY, KYUNGKI-DO

KOREA, REPUBLIC OF KOREA

Additional name(s) & address(es) attached? ☐ Yes ☒ No

PTO  
10/22/02  
JC979

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 4/19/02; 4/19/02

A. Patent Application No.(s)

10,224,933

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Steve Cha

Address: KLAUBER & JACKSON  
411 Hackensack Avenue, 4th Floor  
Hackensack, New Jersey 07601

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

☒ Enclosed

☐ Authorized to be charged to deposit account, if necessary - for overages or underpayments only

8. Deposit account number:

11-1153

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and my attached copy is a true copy of the original document.

Steve Cha, Reg No. 44,069  
Name of Person Signing

Signature

8/21/02  
Date

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded with required cover sheet information to:

Assistant Commissioner for Patents  
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02 FC:581

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Customer No.:23565

Docket No.:

**Assignment of Invention and Patent Application**

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in consideration of TEN (\$10.00) DOLLAR,

- 1) Yu-Sik KIM of  
843, Shindang 4-dong, Chung-gu, Seoul, Republic of Korea
- 2) Joong-Hee LEE of  
124, Chongja-dong, Puntang-gu, Songnam-shi, Kyonggi-do, Republic of Korea

(hereinafter **Assignor**) hereby sells, assigns, transfers, and sets over unto:

**SAMSUNG ELECTRONIC CO., LTD.** of  
**416, MAETAN-DONG, PALDAL-GU, SUWON-CITY, KYUNGKI-DO, KOREA**  
**REPUBLIC OF KOREA**

(hereinafter **Assignee**) the entire right, title and interest for the United States Of America as defined in 35 U.S.C. § 1.00, in and to the invention entitled as:

Multi-Layer Structure For Reducing Capacitance And Manufacturing Method  
Thereof

invented by **Assignor**; the application for United States patent therefor, invented by **Assignor**; any patent or reissues of any patent that may be granted thereon; and any applications which are continuations, continuation-in-part, substitutes, or divisions of said application. **Assignor** authorizes **Assignee** to enter the date of signature and/or Serial Number and Filing Date in the above. **Assignor** also authorizes and requests the Commissioner of Patents and Trademarks to issue any resulting patent(s) to the said **Assignee**, for its interests as **Assignee**, its successors, assigns and legal representatives. The undersigned agrees that the attorney of record in said application shall hereafter act on behalf of said **Assignee**; and **Assignor** further conveys to **Assignee** all priority rights resulting from the above-identified application for United States Patent. **Assignor** agrees to execute all papers, give any required testimony and perform other lawful acts, as deemed essential by **Assignee** to perfect **Assignee's** interest in any resulting patent of the United States, and to acquire, hold, enforce, convey, and uphold the validity of said patent and reissues and extensions thereof, and **Assignee's** interest therein.

**SIGNED ON THE DATES(S) INDICATED BESIDE MY/OUR SIGNATURE(S):**

**Name of First Inventor:** Yu-Sik KIM

Yu-sik KIM

Signature of inventor

Dated: August 19, 2002

WITNESSED: Jong-Hee Kim

**Name of Second Inventor:** Joong-Hee LEE

Joong-Hee Lee

Signature of inventor

Dated: August 19, 2002

WITNESSED: Jong-Hee Kim